

## N-Channel Enhancement Mode Power MOSFET

### Description

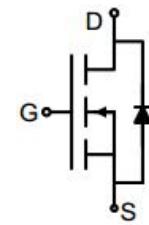
The G28N03D3 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge. It can be used in a wide variety of applications.

### General Features

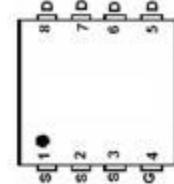
- $V_{DS}$  30V
- $I_D$  (at  $V_{GS} = 10V$ ) 28A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) < 12mΩ
- $R_{DS(ON)}$  (at  $V_{GS} = 4.5V$ ) < 18mΩ
- 100% Avalanche Tested
- RoHS Compliant

### Application

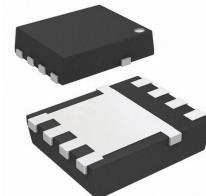
- Power switch
- DC/DC converters



Schematic diagram



pin assignment



DFN3X3-8L

### Ordering Information

| Device   | Package   | Marking | Packaging    |
|----------|-----------|---------|--------------|
| G28N03D3 | DFN3X3-8L | G28N03  | 5000psc/Reel |

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

| Parameter  | Symbol         | Value      | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage                             | $V_{DS}$       | 30         | V    |
| Continuous Drain Current                         | $I_D$          | 28         | A    |
| Pulsed Drain Current<br>(note1)                  | $I_{DM}$       | 112        | A    |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$   | V    |
| Power Dissipation                                | $P_D$          | 23         | W    |
| Operating Junction and Storage Temperature Range | $T_J, T_{stg}$ | -55 To 150 | °C   |

### Thermal Resistance

| Parameter                               | Symbol     | Value | Unit |
|---|------------|-------|------|
| Thermal Resistance, Junction-to-Ambient | $R_{thJA}$ | 65    | °C/W |
| Maximum Junction-to-Case                | $R_{thJC}$ | 5.4   | °C/W |

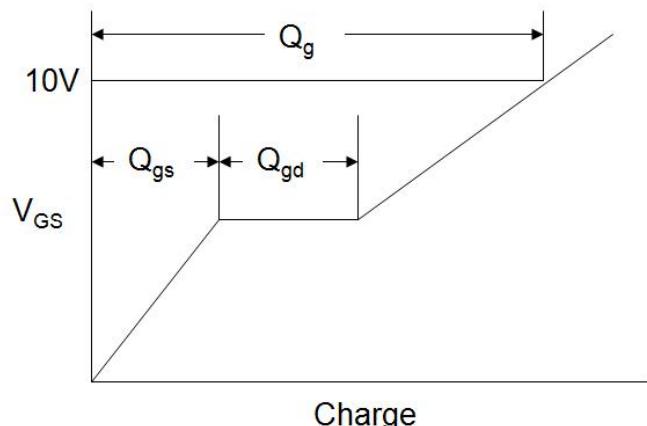
**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

| Parameter                                      | Symbol                      | Test Conditions   | Value |      |           | Unit             |
|--|-----------------------------|---|-------|------|-----------|------------------|
|  |                             |   | Min.  | Typ. | Max.      |                  |
| <b>Static Parameters</b>                       |                             |   |       |      |           |                  |
| Drain-Source Breakdown Voltage                 | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$                               | 30    | --   | --        | V                |
| Zero Gate Voltage Drain Current                | $I_{\text{DSS}}$            | $V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$                         | --    | --   | 1         | $\mu\text{A}$    |
| Gate-Source Leakage                            | $I_{\text{GSS}}$            | $V_{\text{GS}} = \pm 20\text{V}$  | --    | --   | $\pm 100$ | nA               |
| Gate-Source Threshold Voltage                  | $V_{\text{GS}(\text{th})}$  | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$                           | 1     | 2    | 2.5       | V                |
| Drain-Source On-Resistance                     | $R_{\text{DS}(\text{on})}$  | $V_{\text{GS}} = 10\text{V}, I_D = 16\text{A}$                                  | --    | 6.5  | 12        | $\text{m}\Omega$ |
|  |                             | $V_{\text{GS}} = 4.5\text{V}, I_D = 14\text{A}$                                 | --    | 15   | 18        |                  |
| Forward Transconductance                       | $g_{\text{FS}}$             | $V_{\text{GS}} = 5\text{V}, I_D = 10\text{A}$                                   | --    | 2.5  | --        | S                |
| <b>Dynamic Parameters</b>                      |                             |   |       |      |           |                  |
| Input Capacitance                              | $C_{\text{iss}}$            | $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1.0\text{MHz}$      | --    | 896  | --        | $\text{pF}$      |
| Output Capacitance                             | $C_{\text{oss}}$            |   | --    | 145  | --        |                  |
| Reverse Transfer Capacitance                   | $C_{\text{rss}}$            |   | --    | 129  | --        |                  |
| Total Gate Charge                              | $Q_g$                       | $V_{\text{DD}} = 15\text{V}, I_D = 16\text{A}, V_{\text{GS}} = 10\text{V}$      | --    | 20   | --        | $\text{nC}$      |
| Gate-Source Charge                             | $Q_{\text{gs}}$             |   | --    | 2.5  | --        |                  |
| Gate-Drain Charge                              | $Q_{\text{gd}}$             |   | --    | 4.9  | --        |                  |
| Turn-on Delay Time                             | $t_{\text{d}(\text{on})}$   | $V_{\text{DD}} = 15\text{V}, I_D = 16\text{A}, R_G = 3\Omega$                   | --    | 28   | --        | $\text{ns}$      |
| Turn-on Rise Time                              | $t_r$                       |   | --    | 15   | --        |                  |
| Turn-off Delay Time                            | $t_{\text{d}(\text{off})}$  |   | --    | 28   | --        |                  |
| Turn-off Fall Time                             | $t_f$                       |   | --    | 14   | --        |                  |
| <b>Drain-Source Body Diode Characteristics</b> |                             |   |       |      |           |                  |
| Continuous Body Diode Current                  | $I_S$                       | $T_C = 25^\circ\text{C}$  | --    | --   | 28        | A                |
| Body Diode Voltage                             | $V_{\text{SD}}$             | $T_J = 25^\circ\text{C}, I_{\text{SD}} = 16\text{A}, V_{\text{GS}} = 0\text{V}$ | --    | --   | 1.2       | V                |
| Reverse Recovery Charge                        | $Q_{\text{rr}}$             | $I_F = 16\text{A}, V_{\text{GS}} = 0\text{V}$<br>$dI/dt = 100\text{A/us}$       | --    | 10.5 | --        | $\text{nC}$      |
| Reverse Recovery Time                          | $T_{\text{rr}}$             |   | --    | 25   | --        | ns               |

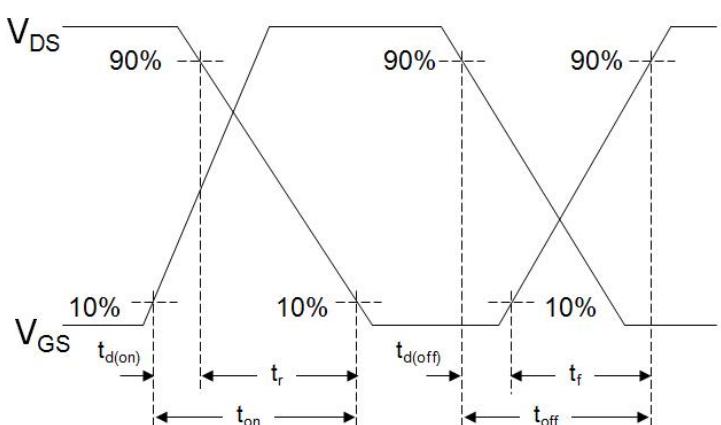
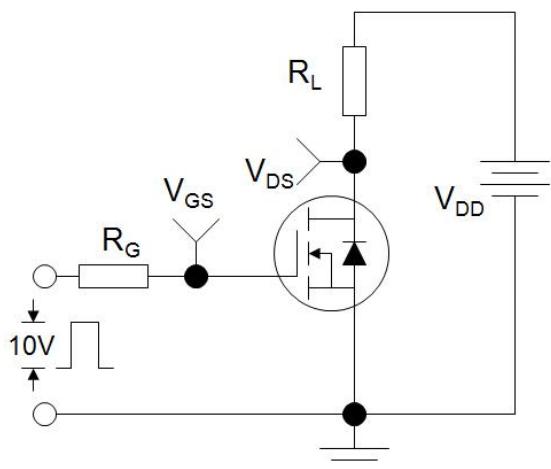
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=30\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$
3. Identical low side and high side switch with identical  $R_G$

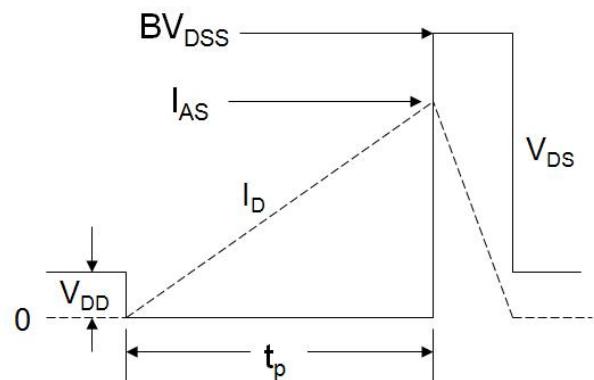
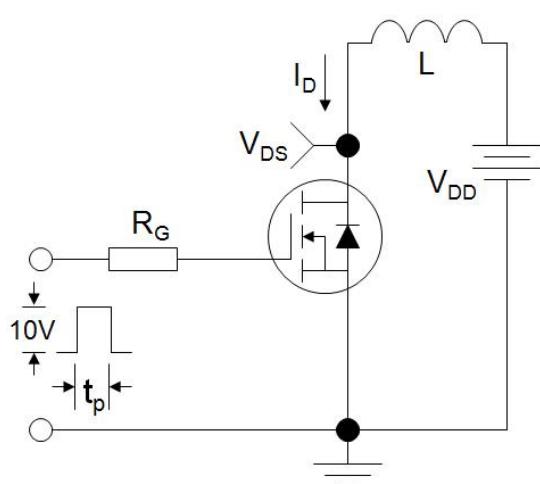
### Gate Charge Test Circuit



### Switch Time Test Circuit

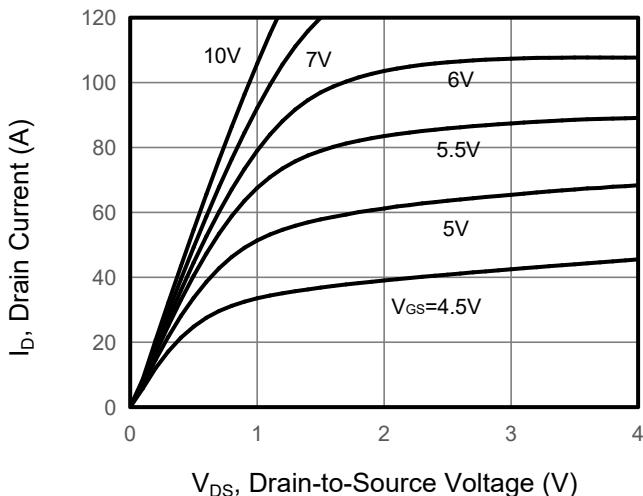


### EAS Test Circuit

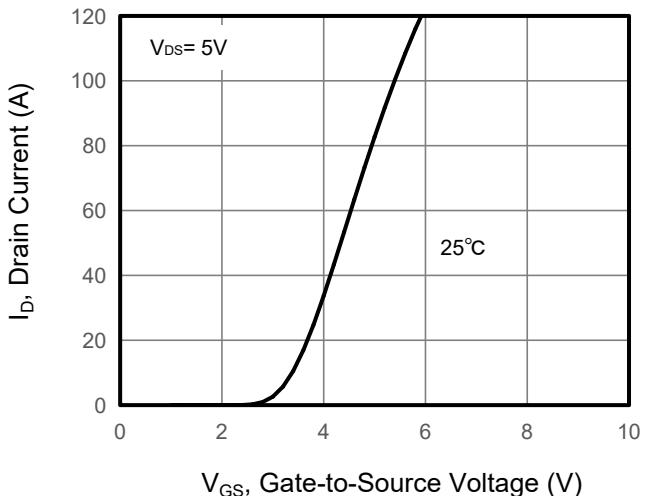


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

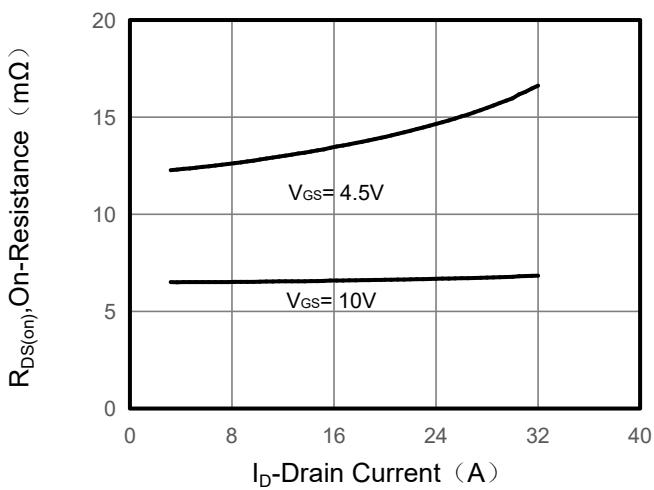
**Figure 1. Output Characteristics**



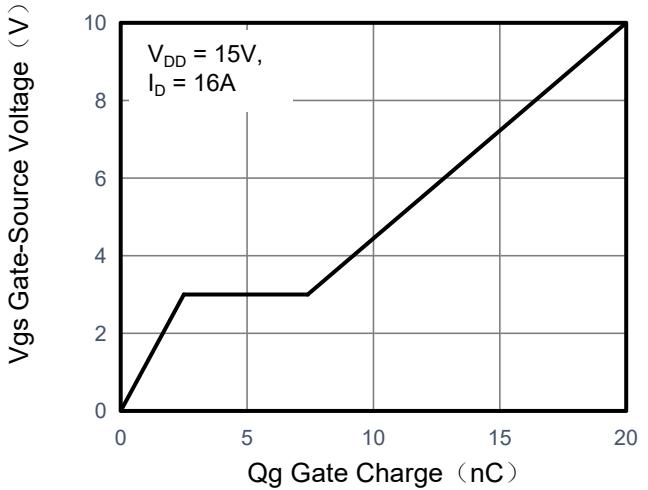
**Figure 2. Transfer Characteristics**



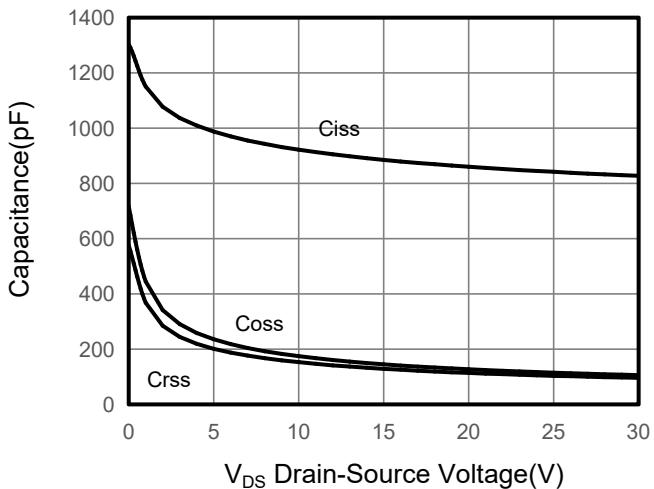
**Figure 3. Drain Source On Resistance**



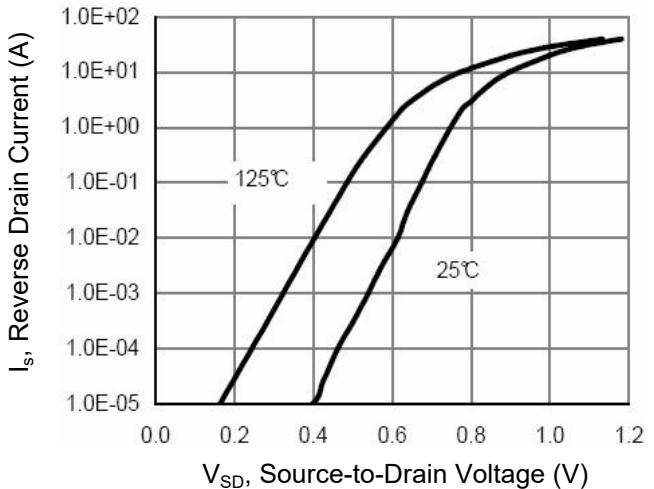
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

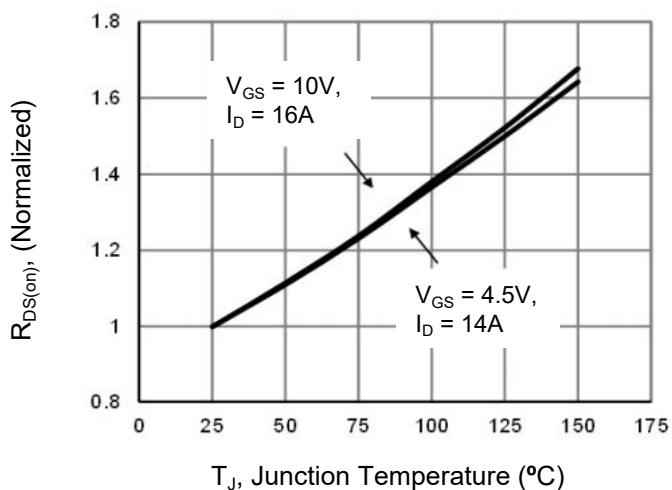


**Figure 6. Source-Drain Diode Forward**

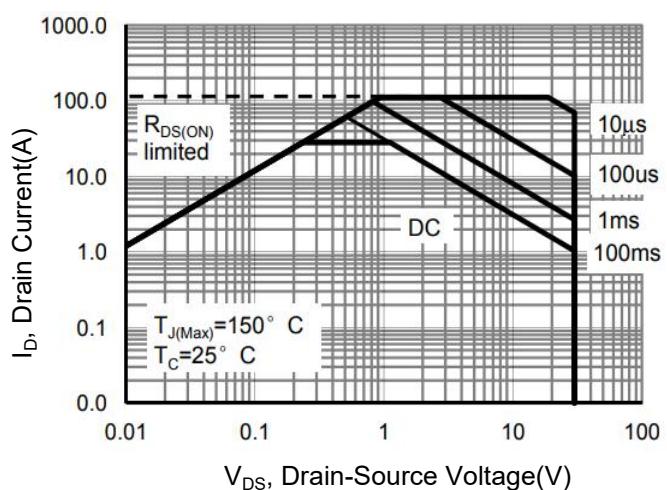


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

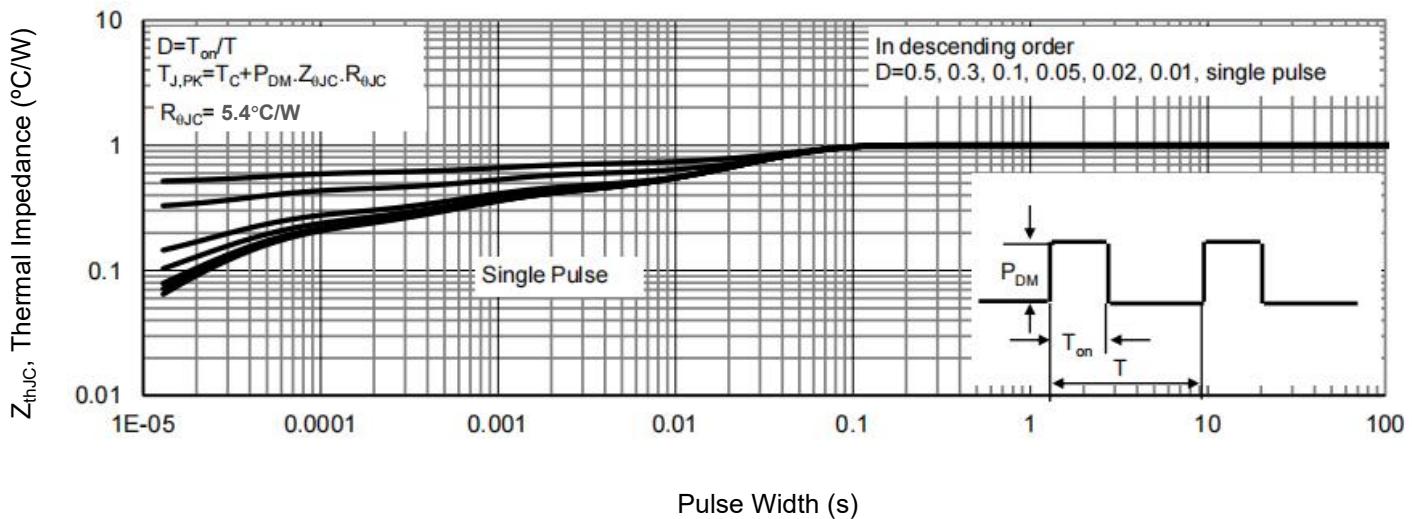
**Figure 7. Drain-Source On-Resistance**

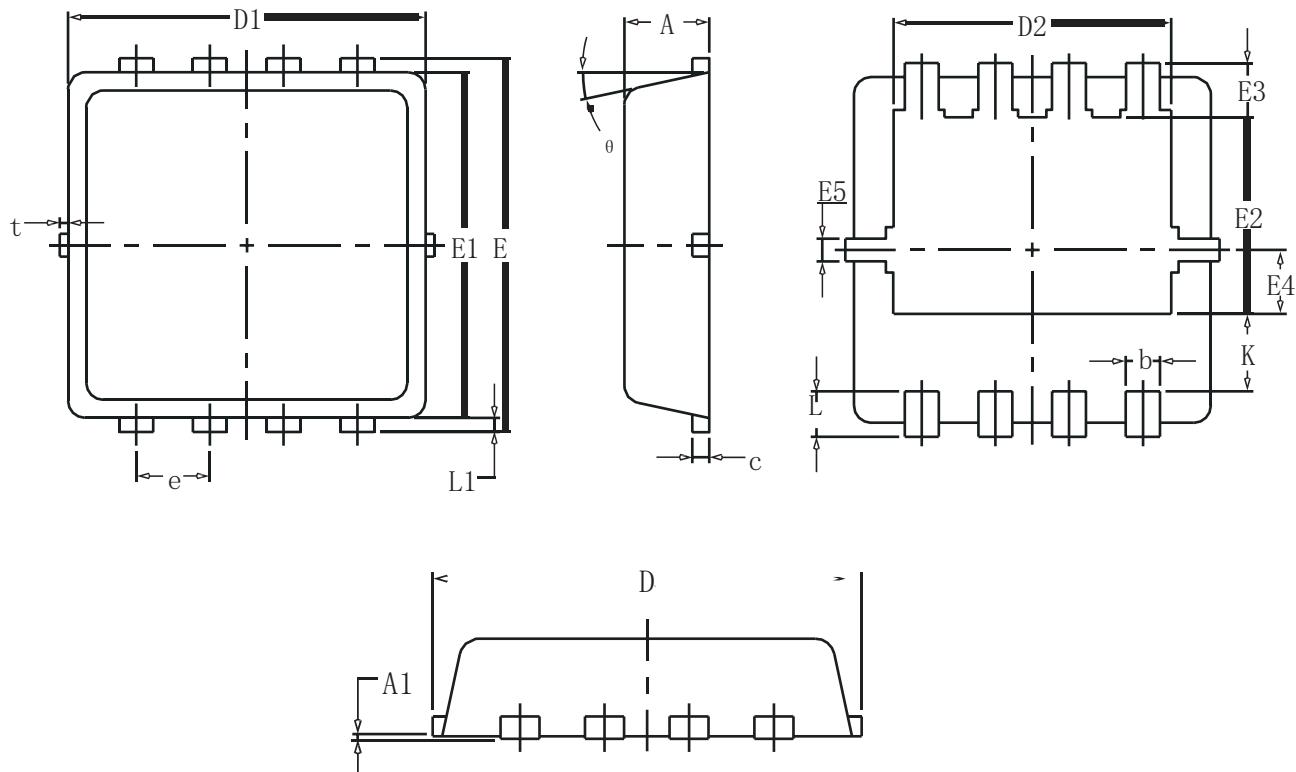


**Figure 8. Safe Operation Area**



**Figure 9. Normalized Maximum Transient Thermal Impedance**



**DFN3x3-8L Package Information**

| SYMBOL | COMMON |       |      |
|--------|--------|-------|------|
|        | MIN    | NOM   | MAX  |
| A      | 0.70   | 0.75  | 0.85 |
| A1     | -      | -     | 0.05 |
| b      | 0.20   | 0.30  | 0.40 |
| c      | 0.10   | 0.152 | 0.25 |
| D      | 3.15   | 3.30  | 3.45 |
| D1     | 3.00   | 3.15  | 3.25 |
| D2     | 2.29   | 2.45  | 2.65 |
| E      | 3.15   | 3.30  | 3.45 |
| E1     | 2.90   | 3.05  | 3.20 |
| E2     | 1.54   | 1.74  | 1.94 |
| E3     | 0.28   | 0.48  | 0.65 |
| E4     | 0.37   | 0.57  | 0.77 |
| E5     | 0.10   | 0.20  | 0.30 |
| e      | 0.60   | 0.65  | 0.70 |
| K      | 0.59   | 0.69  | 0.89 |
| L      | 0.30   | 0.40  | 0.50 |
| L1     | 0.06   | 0.125 | 0.20 |
| t      | 0      | 0.075 | 0.13 |
| θ      | 10°    | 12°   | 14°  |